

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YONG HA WOO	06/30/2014
E-TUNG CHOU	07/02/2014
WEN-LUN LO	06/30/2014
RECEIVING PARTY DATA	
Name:	Zhen Ding Technology Co., Ltd.
Street Address:	No. 6, Lane 28, San Ho Rd., San Shi Village
City:	Tayuan, Taoyuan
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14331330
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ATTORNEY DOCKET NUMBER:	US50985
NAME OF SUBMITTER:	ZHIGANG MA
SIGNATURE:	/Zhigang Ma/
DATE SIGNED:	07/26/2015
Total Attachments: 3	
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source=US50985150723ASM#page3.tif	

ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

1. YONG HA WOO, residing at Kwang myung, Korea
2. ZHEN DING
TECHNOLOGY CO., LTD., residing at Tayuan, Taoyuan, Taiwan
3. WEN-LUN LO, residing at Tayuan, Taoyuan, Taiwan
4. _____, residing at _____
5. _____, residing at _____
6. _____, residing at _____
7. _____, residing at _____
8. _____, residing at _____

hereby sell(s), assign(s) and transfer(s) unto: **ZHEN DING TECHNOLOGY CO., LTD.** having a principal place of business at **No. 6, Lane 28, San Ho Rd., San Shi Village, Tayuan, Taoyuan, Taiwan, R.O.C.** hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as **CORELESS PACKAGE STRUCTURE AND METHOD FOR MANUFACTURING** for which the undersigned

☐ previously executed --- Ser. No. _____ and filing date of _____

☒ is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1.	<u>YONG HA WOO</u>	<u>June 30, 2014</u>
	YONG HA WOO	Date
2.	<u>E-TUNG CHOU</u>	<u></u>
	E-TUNG CHOU	Date
3.	<u>WEN-LUN LO</u>	<u>2014/06/30</u>
	WEN-LUN LO	Date
4.	<u></u>	<u></u>
		Date
5.	<u></u>	<u></u>
		Date
6.	<u></u>	<u></u>
		Date
7.	<u></u>	<u></u>
		Date
8.	<u></u>	<u></u>
		Date
9.	<u></u>	<u></u>
		Date

1.	_____	_____	Date
2.	<u>Lin-Ying Wong</u> LIN-YING WONG	<u>July 2, 2014</u>	Date
3.	_____	_____	Date
4.	_____	_____	Date
5.	_____	_____	Date
6.	_____	_____	Date
7.	_____	_____	Date
8.	_____	_____	Date
9.	_____	_____	Date